

WHAT IS CLAIMED IS

1. An improved thermal module adopted for use on an electronic device that generates a smaller amount of heat, comprising:
 - a heat-absorbing portion for absorbing the heat generated by the electronic device during
5 operation;
 - a heat-transmitting portion having one end connecting to the heat-absorbing portion to deliver the heat absorbed by the heat-absorbing portion; and
 - a heat-conducting portion connecting to another end of the heat-transmitting portion for dispersing the heat delivered from the heat-transmitting portion to ambience.
- 10 2. The improved thermal module of claim 1 further having a fixing structure and a plurality of joining elements, the fixing structure including a flexible member which is a thin plate to cover the heat-absorbing portion and has outer rims to form a fastening structure to couple with the joining elements to fasten the heat-absorbing portion.
3. The improved thermal module of claim 1, wherein the electronic device is selected from a
15 group consisting of a video device and a VGA card.
4. The improved thermal module of claim 1, wherein the heat-transmitting portion is a heat pipe.
5. The improved thermal module of claim 1, wherein the heat-conducting portion is a radiation fin that has a large surface area to improve heat dissipation effect.
- 20 6. The improved thermal module of claim 5, wherein the radiation fin has a radiation deck which has struts extending outwards.
7. The improved thermal module of claim 5, wherein the radiation fin has a radiation deck which has undulate fins extending outwards.
8. The improved thermal module of claim 2, wherein the fixing structure includes a plurality
25 of fastening holes to fasten to the joining elements by screw coupling.
9. The improved thermal module of claim 2, wherein the flexible member is formed in a cross section selecting from a group consisting of a Γ -shape, a protrusive shape and an indented shape.
- 30 10. An improved thermal module adopted for use on an electronic device that generates a smaller amount of heat, comprising:
 - a heat-absorbing portion for absorbing the heat generated by the electronic device during operation;

a heat-transmitting portion having one end connecting to the heat-absorbing portion to deliver the heat absorbed by the heat-absorbing portion;

a heat-conducting portion connecting to another end of the heat-transmitting portion for dispersing the heat delivered from the heat-transmitting portion to ambience; and

5 a fixing structure which includes a flexible member and a plurality of joining elements, the flexible member being a thin plate to cover the heat-absorbing portion and has outer rims to form a fastening structure to couple with the joining elements to fasten the heat-absorbing portion.

10 11. The improved thermal module of claim 10, wherein the electronic device is selected from a group consisting of a video device and a VGA card.

12. The improved thermal module of claim 10, wherein the heat-transmitting portion is a heatpipe.

13. The improved thermal module of claim 10, wherein the heat-conducting portion is a radiation fin that has a large surface area to improve heat dissipation effect.

15 14. The improved thermal module of claim 13, wherein the radiation fin has a radiation deck which has struts extending outwards.

15. The improved thermal module of claim 13, wherein the radiation fin has a radiation deck which has undulate fins extending outwards.

20 16. The improved thermal module of claim 10, wherein the fastening structure includes a plurality of fastening holes to fasten to the joining elements by screw coupling.

17. The improved thermal module of claim 10, wherein the flexible member is formed in a cross section selecting from a group consisting of a Γ -shape, a protrusive shape and an indented shape.